

Section

MV Semi-conductor

Application

Field



PRODUCT BENEFITS

Back-iron to set the pitch of the tool in order to get a good result over the insulation

TOOL CAPACITY

Diameter 38 - 60 mm
1,496 - 2,362 inch

Max cutting depth 5 mm / 0,197 in

TOOL DIMENSIONS

Length 425 mm

Width 105 mm

Height 85 mm

Weight without box 2 Kg

Packaging None

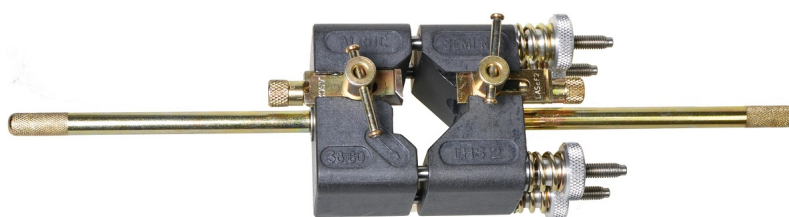
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Monofuncton tool for bonded semiconductor

TO DO WHAT

The LHS2 enables the user to remove bonded semiconductor



Spare part

LASC2 - Spare blade for bonded semiconductor

Associated tool

LH2 - Monofunction tool for insulation

PRG3-C20L222830 - Pliers for MV cable outer sheath with 3 adjustable longitudinal cutting depth

BMF2 - Thrust to stop the tool

LHS2



Part Number	Diameter	Tool capacity	Dimensions			Packaging
		Max cutting depth	Length	Width	Height	
LHS2	38 - 60 mm 1,496 - 2,362 in	5 mm / 0,197 in	425 mm 16,732 in	105 mm 4,134 in	85 mm 3,346 in	none
LHS3	60 - 80 mm 2,362 - 3,150 in	10 mm / 0,394 in	460 mm 18,110 in	130 mm 5,118 in	85 mm 3,346 in	none
LHS4	80 - 110 mm 3,150 - 4,331 in	12 mm / 0,473 in	640 mm 25,197 in	155 mm 6,102 in	95 mm 3,740 in	none
LHS5	100 - 140 mm 3,937 - 5,512 in	8 mm / 0,315 in	730 mm 28,740 in	195 mm 7,677 in	115 mm 4,528 in	none